

### Small Signal Diode



#### Features

- ↪ Meet IEC61000-4-2 (ESD) ±15kV (air), ±8kV (contact)
- ↪ Meet IEC61000-4-4 (EFT) rating. 40A (5/50ns)
- ↪ Protects one bidirectional I/O line
- ↪ Working Voltage : 5V
- ↪ Pb free version, RoHS compliant, and Halogen free

#### Mechanical Data

- ↪ Case : SOD-323 small outline plastic package
- ↪ Terminal: Matte tin plated, lead free., solderable per MIL-STD-202, Method 208 guaranteed
- ↪ High temperature soldering guaranteed: 260°C/10s
- ↪ Mounting position: Any
- ↪ Weight : 4.85±0.5 mg
- ↪ Marking Code : AC

#### Applications

- ↪ Cell Phone Handsets and Accessories
- ↪ Notebooks, Desktops, and Servers
- ↪ Keypads, Side Keys, USB 2.0, LCD Displays
- ↪ Portable Instrumentation
- ↪ Microprocessor based equipment

#### Ordering Information

| Part No.   | Package | Packing      | Packing Code | Marking |
|------------|---------|--------------|--------------|---------|
| TESDC5V0LC | SOD-323 | 3K / 7" Reel | RRG          | AC      |

#### Maximum Ratings and Electrical Characteristics

Rating at 25°C ambient temperature unless otherwise specified.

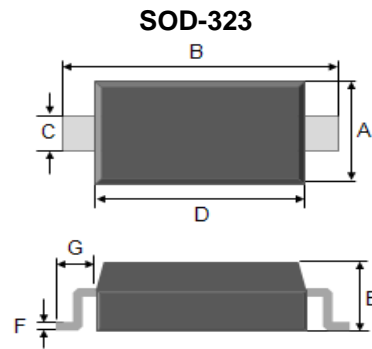
##### Maximum Ratings

| Type Number  | Symbol                            | Value        | Units |
|--|-----------------------------------|--------------|-------|
| Peak Pulse Power (tp=8/20µs waveform)                          | P <sub>PP</sub>                   | 350          | W     |
| ESD per IEC 61000-4-2 (Air)<br>ESD per IEC 61000-4-2 (Contact) | V <sub>ESD</sub>                  | ±15<br>±8    | KV    |
| Junction and Storage Temperature Range                         | T <sub>J</sub> , T <sub>STG</sub> | -55 to + 150 | °C    |

##### Electrical Characteristics

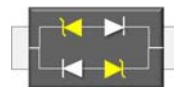
| Type Number               | Symbol            | Min       | Max  | Units |
|---------------------------|-------------------|-----------|------|-------|
| Reverse Stand-Off Voltage | V <sub>RWM</sub>  | -         | 5    | V     |
| Reverse Breakdown Voltage | V <sub>(BR)</sub> | 6         | -    | V     |
| Reverse Leakage Current   | I <sub>R</sub>    | -         | 5    | µA    |
| Clamping Voltage          | V <sub>C</sub>    | -         | 9.8  | V     |
|                           |                   | -         | 18.3 |       |
| Junction Capacitance      | C <sub>J</sub>    | 1.2(Typ.) |      | pF    |

Notes: 1. The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application.

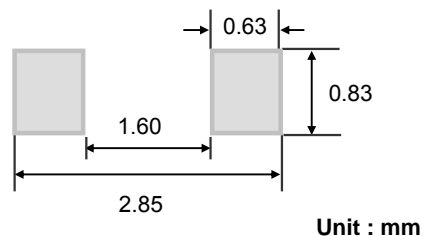


| Dimensions | Unit (mm) |      | Unit (inch) |       |
|------------|-----------|------|-------------|-------|
|            | Min       | Max  | Min         | Max   |
| A          | 1.20      | 1.40 | 0.047       | 0.055 |
| B          | 2.50      | 2.70 | 0.098       | 0.106 |
| C          | 0.25      | 0.35 | 0.010       | 0.014 |
| D          | 1.60      | 1.80 | 0.063       | 0.071 |
| E          | 0.80      | 0.90 | 0.031       | 0.035 |
| F          | 0.08      | 0.15 | 0.003       | 0.006 |
| G          | 0.19 REF  |      | 0.475 REF   |       |

#### Pin Configuration



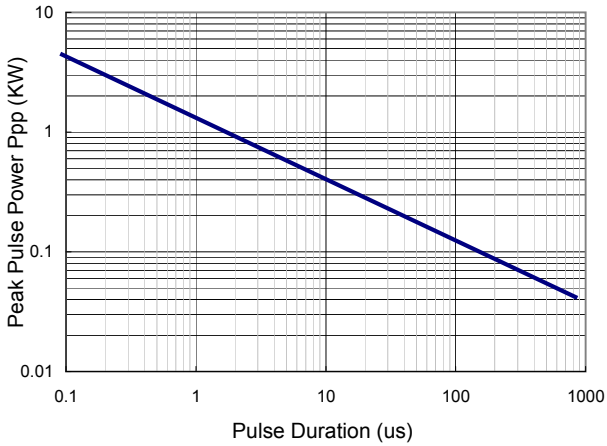
#### Suggested PAD Layout



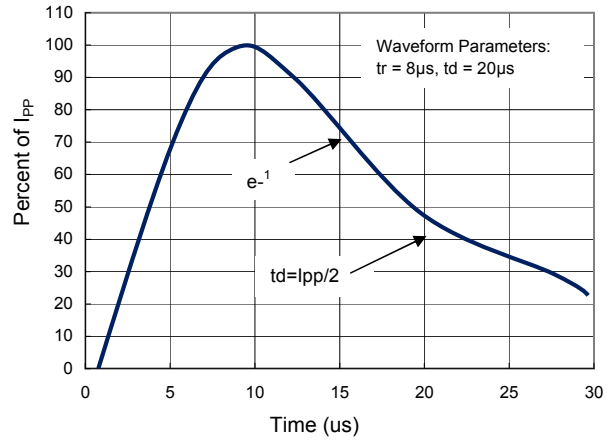
**Small Signal Diode**

**Rating and Characteristic Curves**

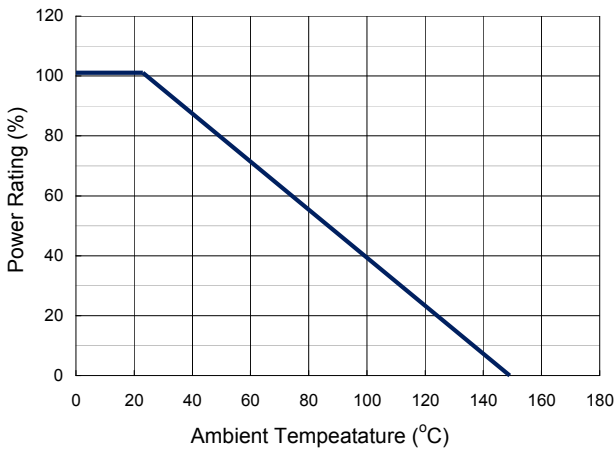
**FIG 1 Non-Repetitive Peak Pulse Power vs. Pulse Time**



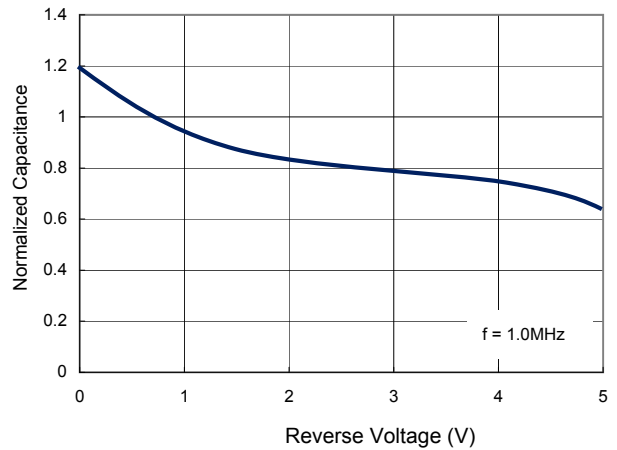
**FIG 2 Pulse Waveform**



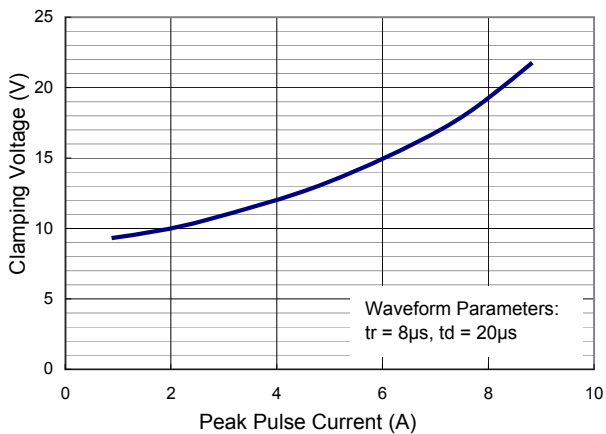
**FIG 3 Admissible Power Dissipation Curve**



**FIG 4 Typical Junction Capacitance**



**FIG 5 Clamping Voltage vs. Peak Pulse Current)**



## Small Signal Diode

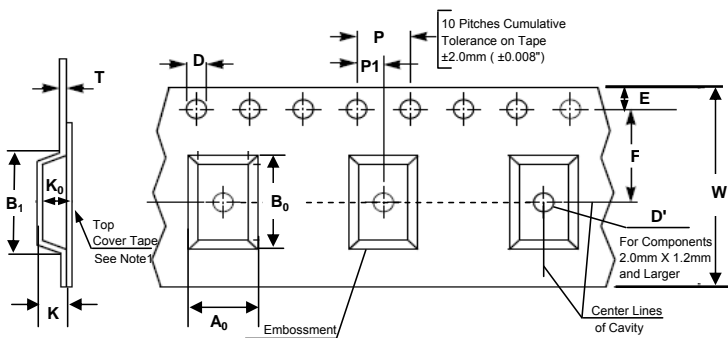
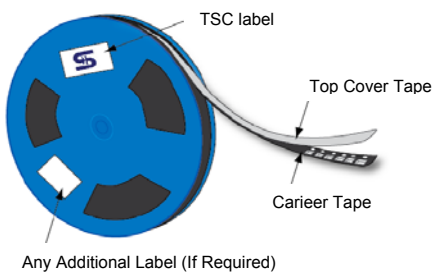
### Applications Information

- ◇ Designed to protect one data, I/O, or power supply line.
- ◇ Designed to protect sensitive electronics from damage or latch-up due to ESD
- ◇ Designed to replace multilayer varistors (MLVs) in portable applications
- ◇ Offers superior electrical characteristics such as lower clamping voltage and no device degradation when compared to MLVs
- ◇ The combination of small size and high ESD surge capability makes them ideal for use in portable applications.

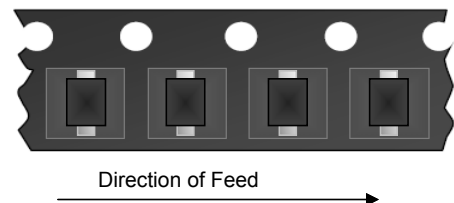
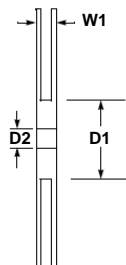
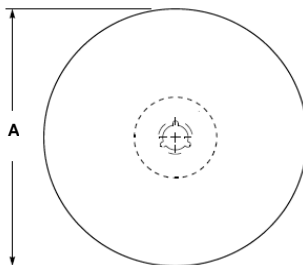
### Circuit Board Layout Recommendations

- Good circuit board layout is critical for the suppression of ESD induced transients.
- ◇ Place the ESD Protection Diode near the input terminals or connectors to restrict transient coupling.
  - ◇ Minimize the path length between the ESD Protection Diode and the protected line.
  - ◇ Minimize all conductive loops including power and ground loops.
  - ◇ The ESD transient return path to ground should be kept as short as possible.

### Tape & Reel specification



| Item                   | Symbol | Dimension (mm) |
|------------------------|--------|----------------|
| Carrier depth          | K      | 2.40 Max.      |
| Sprocket hole          | D      | 1.50 +0.10     |
| Reel outside diameter  | A      | 178 ± 1        |
| Reel inner diameter    | D1     | 50 Min.        |
| Feed hole width        | D2     | 13.0 ± 0.5     |
| Sprocket hole position | E      | 1.75 ± 0.10    |
| Punch hole position    | F      | 3.50 ± 0.05    |
| Sprocket hole pitch    | P0     | 4.00 ± 0.10    |
| Embossment center      | P1     | 2.00 ± 0.10    |
| Overall tape thickness | T      | 0.6 Max.       |
| Tape width             | W      | 8.30 Max.      |
| Reel width             | W1     | 14.4 Max.      |



Note 1:  $A_0$ ,  $B_0$ , and  $K_0$  are determined by component size. The clearance between the components and the cavity must be within 0.05 mm min. to 0.5 mm max. The component cannot rotate more than 10° within the determined cavity.

Note 2: If  $B_1$  exceeds 4.2 mm (0.165") for 8 mm embossed tape, the tape may not feed through all tape feeders.